

Layer	Name	Material	Thickness	Constant	Board L	Layer	Stack
1	Top Overlay	Solder					
2	Top Solder	Solder Resist	0.012in	3.5			
3	Top Layer	Copper		0.035in			
4	Pre-Layer 1	FR4 0.35mm/35,35 copper		0.35in			
5	Pre-Layer 1	Copper		0.2in			
6	Dielectric2	FR4 0.22in		0.22in			
7	Mid-Layer 2	Copper		0.35in			
8	Dielectric3	FR4 0.35mm/35,35 copper		0.35in			
9	Signal Layer 1	Copper		0.35in			
10	Dielectric 4	FR4 0.22in		0.22in			
11	Signal Layer 2	Copper		0.35in			
12	Dielectric 5	FR4 0.35mm/35,35		0.200in			
13	Bottom Layer	Copper		0.035in			
14	Bottom Solder	Solder		0.012in			
15	Bottom Overlay	Solder Resist		3.5			

Supplementary Note:
This board is formed creating a 4 layer board and then bonding bottom core and top prepreg to the fabricated 4-layer board.
This process will create a 5-layer structure with 5 Cu layers and two drill holes. One of the Cu layers is drilled, plating to 0.5 Oz Cu is required. The bottom core and Cu are then bonded and drilled. Plated through holes should then be plated to 0.5 Oz Cu (for the drill hole pairs between top and bottom layers). The silkscreen and chemical finishing should be completed as final processing steps.

Note: board will go through (2) top 0.5 Oz plating processes.
Top & Bottom Layers: finished copper weight 35um +plating=60um

[illegible]

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